Feedpool Technology Co., Ltd.

Website: www.feedpool.com

Technical Data Sheet

FeedBond® EP-3600-A8-1

11S095

Non-conductive Die Attach Adhesive

Description:

FeedBond®EP-3600-A8-1 one-component, translucent epoxy adhesive is developed for optoelectronic packaging application. This adhesive can be used for small die sized chip LED and can be applied to automatic die attach equipment.

Application Package:

LED Chip, GaN Blue and white LED Chip bonding etc

Characteristics:

- No yellowing due to heat and light
- Middle viscosity that is adaptable to conventional processing methods such as pin transfer and dispensing.

UNCURED PROPERTIES		**TEST DESCRIPTION**	**TEST METHOD**
Appearance	Translucent		
Viscosity @ 25°C	16000cps	Brookfield DV-III/CP-51 @ 5rpm	FT-P006
Thixotropic Index @ 25°C	4.8	Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc. @ 5rpm	FT-P008
Grind	< 10μm	Grind meter	FT-P026
Moisture Content	< 0.7 %	25°C/24hours	FT-P002
Work Life @ 25°C	48hrs	25% increase in visc. @ 5rpm	FT-P024
Shelf Life@ -40°C	6months		FT-P018
CURE CONDITION		**TEST DESCRIPTION**	**TEST METHOD**
Standard Cure Condition		90 minutes in oven @150°C 60 minutes in oven @160°C	

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

FeedBond® EP-3600-A8-1

PHYSIOCHEMICAL PROPERTIES	**TEST DESCRIPTION**	**TEST METHOD**
Glass Transition Temperature (Tg) 150℃	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion Below Tg(α1) 62ppm/℃ Above Tg(α2) 159ppm/℃	TMA Expansion Mode	FT-M016
Dynamic Tensile Modulus @25℃ 1988MPa @150℃ 101MPa @250℃ 44MPa	Dynamic Mechanical Thermal Analysis using <1.6 mm thick specimen	FT-M019A
Thermal conductivity 0.23W/mK	Hot Disk	FT-P022
MECHANICAL PROPERTIES-POST CURE	**TEST DESCRIPTION**	**TEST METHOD**
Die Shear Strength @ 25°C >150 g/die	11mil × 11mil die on Ag Leadframe	FT-M012

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

Instruction

Thawing

Place the container to stand vertically for 60mins.**DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -40°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond® adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.